

DO NOT ENTER: /SM/

4/5/2007

**IN THE CLAIMS**

Please amend the claims as follows.

1.-35. (Cancelled)

36. (Previously Presented) A device comprising:

a dispenser configured to release a chemical toward an edge bead of a substrate; and  
a splash controller concentrically positioned at least partially around said dispenser and  
physically unattached from the edge bead, the splash controller being configured to draw  
the chemical from at least one surface of the substrate and toward said splash controller,  
wherein said splash controller is configured to generate a gas pressure around the edge  
bead that is lower than an ambient gas pressure, and wherein said splash controller is  
configured to physically intercept the chemical.

37. (Previously Presented) The device in claim 36, wherein the splash controller is around the  
edge bead.

38. (Previously Presented) The device of claim 36, wherein the splash controller completely  
surrounds said dispenser.

39. (Previously Presented) The device of claim 36, wherein the dispenser has a diameter smaller  
than a diameter of the splash controller.

40. (Previously Presented) The device of claim 36, wherein said dispenser is configured to  
release a chemical on a first side of a wafer and a second side of the wafer toward an edge bead,  
wherein the splash controller completely surrounds said dispenser.

41. (Previously Presented) A device comprising:

    a dispenser configured to release a chemical toward an edge bead on a semiconductor substrate; and

    a splash controller including a vacuum port, wherein the vacuum port is concentrically positioned about the dispenser, wherein the vacuum port is configured to generate a gas pressure around the edge bead and the dispenser, the generated gas pressure being sufficiently lower than an ambient gas pressure to draw the chemical from at least one surface of the substrate and toward the splash controller, wherein the dispenser has a smaller diameter than the vacuum port, and wherein the splash controller is configured to physically intercept the chemical.

42. (Previously Presented) The device of claim 41, wherein said dispenser is to release a chemical on a first side of a semiconductor substrate.

43. (Previously Presented) The device of claim 42, wherein said dispenser is to release a chemical on a second side of a semiconductor substrate.

44. (Previously Presented) The device of claim 43, wherein said dispenser is to release a solvent.

45. (Previously Presented) The device of claim 42, wherein said dispenser is to release a photoresist solvent.